

C1206X132F2TACTU

Aliases (C1206X132F2TAC7800) SMD Comm X8G HT150C Flex, Ceramic, 1,300 pF, 1%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	20 mg
Shelf Life	78 Weeks
MSL	1

	Specifications	
1206	Capacitance	1,300 pF
3.3mm +/-0.4mm	Measurement Condition	1 kHz 1.0Vrms
1.6mm +/-0.35mm	Tolerance	1%
0.9mm +/-0.20mm	Voltage DC	200 VDC
1.5mm MIN	Dielectric Withstanding Voltage	500 VDC
0.6mm +/-0.25mm	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
T&R, 180mm, Plastic Tape 4000	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
	Dissipation Factor	0.1% 1 kHz 1.0Vrms

Aging Rate

Insulation Resistance

 Dimensions

 Chip Size
 1206

 L
 3.3mm +/-0.4mm

 W
 1.6mm +/-0.35mm

 T
 0.9mm +/-0.20mm

 S
 1.5mm MIN

 B
 0.6mm +/-0.25mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

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0% Loss/Decade Hour: Referee

Time is 1000 Hours

100 GOhms